

We are delighted to have completed the adjudication of the many high quality Abstracts submitted to the Electronics System-Integration Technology Conference (ESTC-2008). The result is 184 oral papers structured into six parallel tracks and 77 Poster displays which will also have scheduled short presentation slots in the Conference.

We expect over 500 international delegates which will contribute to a lively conference and a very healthy attendance at the exhibits. I encourage CPMT members globally to attend ESTC-2008 and companies to exhibit.

This will be a fulfillment of the active collaboration with IMAPS-Europe and CPMT HQ which was initiated from here, and a gratifying outcome of the efforts to architect both this collaboration and the involvement of national and regional chapters in such international events.

Visit us: www.estc.biz for a full advance program.

Student Chapter Reports:



Chalmers University of Technology IEEE CPMT Student Chapter

Submitted by Sijia Jiang, IEEE CPMT Student Chapter
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The Chalmers University of Technology IEEE CPMT Student Chapter mainly focuses on electrical packaging, but also including other electronics fields of knowledge such as MEMS and displays. The members in the chapter, who mostly are the students of the international master's program in microtechnology supervised by Professor Johan Liu in Chalmers University of Technology, come from multiple cultures and knowledge backgrounds, and gather here in the group to share their knowledge such as electronics, physics and materials science to acquaint with the interesting and promising technology of packaging.

During the study year 2007/2008, we opened the door of electrical packaging when attending the lecture of introduction of microsystem packaging, where the lecturers Johan Liu and Cristina Andersson brought the whole group to enjoy a funny journey into the field. And in October 2007, we paid a visit to the SAAB Space AB, which is a distinguished company in Sweden, famous with its aircrafts, automobiles and so forth. Following the presentation about the company by the Technical Manager Dr Stanley Mattson, we were guided around to see the testing and analysis facilities.

Apart from the lectures and SAAB visit, there were two fascinating guest lectures, one was about the optical products and packaging of optical devices by Dr Arne Alping at Ericsson and another was about the conductive adhesives and MEMS packaging, by Dr Masahiro Inoue, Osaka University, Japan and Katrin Persson, Iomago, respectively.

As to the social activities, a dish party as a tradition in the chapter was held in MC2 building, Chalmers University

during which everybody brought diversified food prepared by ourselves and enjoyed the beverage "sponsored" by Chalmers University of Technology. Additionally, our chapter members organized a "movie and culture" party to communicate the different cultures in our respective home countries and also other activities to enhance our friendship.

So far, the members in the chapter have gained rather enough knowledge of packaging, in the upcoming autumn, it is the time we are going to participate in some projects with more practical experiments, which are believed to make us more engineer-like and put the theory into practical challenges.

Dish Party as a Student Chapter Tradition of Our Chapter



Dish Party as a Tradition of Our Chapter in MC2 Building (Year 2005 ~ 2007)



During October, 2007, for the student members of year 2007 / 2008



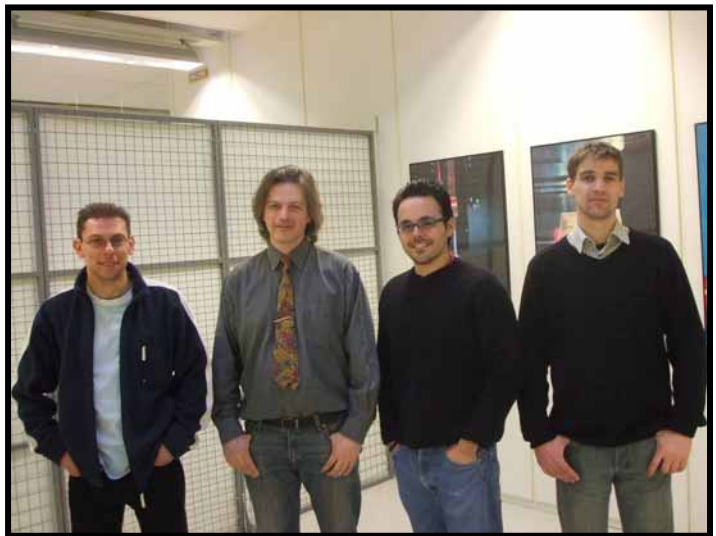
During November, 2007, for the student members of year 2006 / 2007



Visit to Frontside Electronics AB, during February, 2007



During December, 2005, for student members of the year 2005 / 2006



Visit to MYDATA Automation AB, Bromma, Sweden, March, 2007.

Company Visits



Visit to SAAB Space AB, September, 2006, for the student members of the year 2006 / 2007

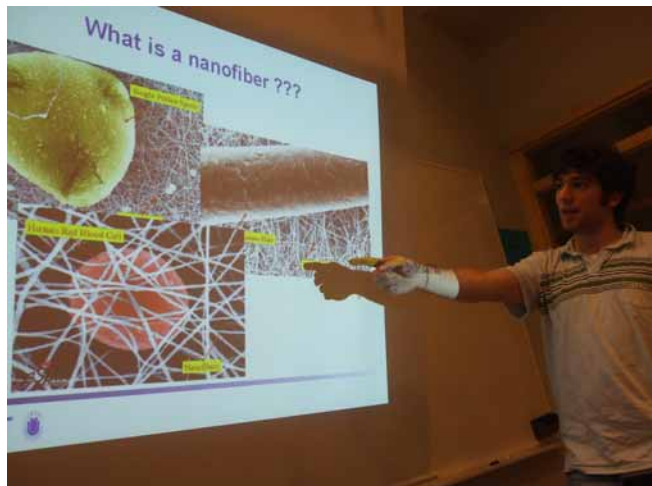
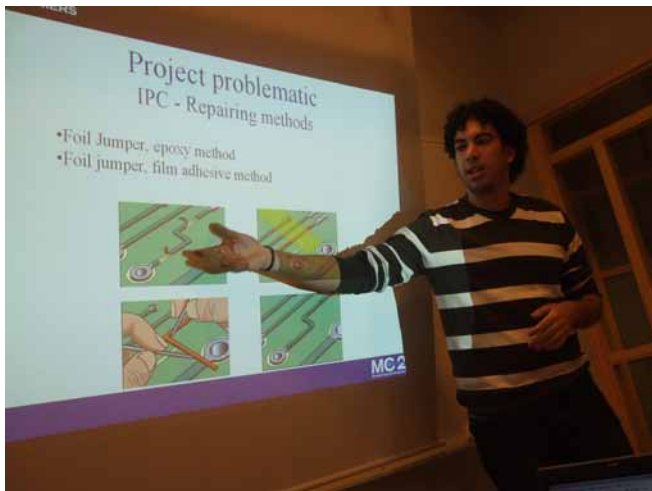


Visit to SAAB Space AB, during September, 2005 for the student members of the year 2005 / 2006



Guest lecture about MEMS from Iomega during October, 2007 for the student members of year 2007 / 2008

Project Seminars during January thru April, 2007



Student members of year 2006/2007 are presenting



Professor Johan Liu is discussing with the student members of year 2005/2006 during Project Seminar held in March, 2006

Conference Reviews:

58th Electronic Components and Technology Conference (ECTC) Update

Submitted by Dr. Rajen Dias, Asst. Program Chair

The 58th ECTC that will be held at Disney's Contemporary Resort in Lake Buena Vista, Florida, USA during May 27 to 30, 2008, has received 616 technical abstracts, a record number for the technical program. The technical program will feature over 300 high quality technical papers, presented in 36 oral sessions, two poster sessions and a special student poster session. The papers will cover a wide spectrum of topics including advanced packaging, interconnections, electronic components, materials, processing, assembly, manufacturing, optoelectronics, quality and reliability, modeling, simulation and emerging technology that focuses on nano-technology, biomedical and flexible electronics.

The technical program is complemented by 16 professional development courses, a plenary session, a panel discussion session and a CPMT seminar session. In addition, there is a technical exhibit corner where over 50 leading companies, primarily in the electronics components, materials, thermal and packaging fields exhibit their latest technologies and products. The conference allows ample opportunities to network and meet leading experts in the field.

For more information on 58 ECTC, please visit www.ectc.net

ECTC 2008 Professional Development Courses Tuesday, May 27, 2008

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